

IN THE CLAIMS:

Please amend Claim 5 and add new Claim 12, as shown below.

1 to 4. (Cancelled)

5. (Currently Amended) An image pickup apparatus comprising:

a lead of a flexible wiring film;

an image pickup element chip electrically connected to the lead at an electrical connection point; and

a cover glass for protecting a surface of the image pickup element chip,

wherein the lead, the image pickup element chip, and the cover glass are sealed with a sealant in a peripheral portion of the image pickup element chip,

wherein the lead has a hole formed in a portion of the lead in contact with the sealant, the portion of the lead being between the electrical connection point and an area outer end of the lead bonded to an insulating base film, and

wherein a part of the hole is positioned outside the cover glass, and

wherein the lead has a thickness of not greater than 35 μm .

6 and 7. (Cancelled)

8. (Previously Presented) The image pickup apparatus according to Claim 5, wherein at least one of a layer for preventing reflection of external light and a layer for preventing multiple reflection is formed between the lead and the cover glass.

9. (Previously Presented) An image pickup system comprising:
the image pickup apparatus according to Claim 5;
an optical system for focusing light on the image pickup apparatus; and
a signal processing circuit for processing an output signal from the image pickup apparatus.

10 and 11. (Cancelled)

12. (New) The image pickup apparatus according to Claim 5, wherein the thickness of the lead is within the range of 18 μm to 35 μm .